

Part Number:
KH-3030175-Y1

 Checker/Date
Henry
06/01/18'

 Inspector/Date
Henry
06/01/18'

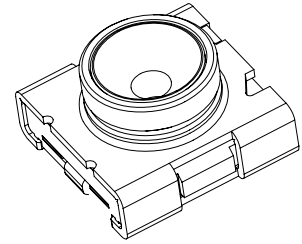
 Maker/Date
SAM
06/01/18'

1、Overview

This product is applied to RF circuits and provides a switch interface for circuit tests, And it's the first type of the "MINI RF CONNECTOR".

2、Technology Parameters

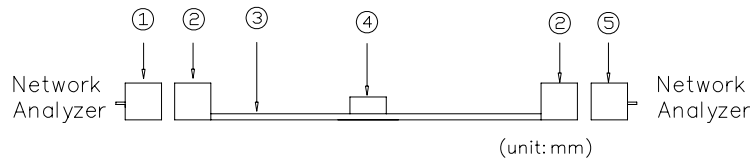
2.1 Rated Voltage	250V AC
2.2 Frequency Range	0~6GHz
2.3 Impedance	50Ω
2.4 Operating Temperature	-40°C ~ +85°C



3、Electrical Performance

3.1 Insulation Resistance	500MΩ
3.2 Dielectric Withstanding Voltage	300V AC
3.3 Contact Resistance	120 mΩ max
3.4 Voltage Standing Wave Ratio(VSWR)	1.2 max (DC~3GHz), 1.3 max (3~6GHz)

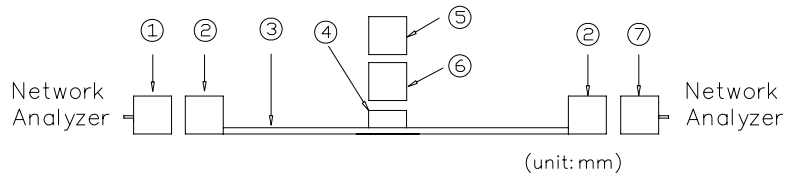
3.4.1 Test Methods:



- | | |
|-------------------|-------------|
| ① Port 1 | ④ 818000251 |
| ② SMA Jack | ⑤ Port 2 |
| ③ Microstrip line | |

3.5 Isolation 20dBmin (DC~3GHz), 15dBmin (3~6GHz)

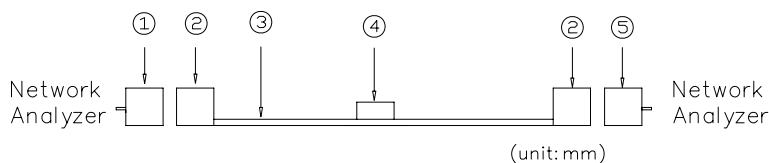
3.5.1 Test Methods:



- | | |
|-------------------|-----------------------------------|
| ① Port 1 | ④ 818000251 |
| ② SMA Jack | ⑤ Termination |
| ③ Microstrip line | ⑥ Probe for automatic measurement |
| | ⑦ Port 2 |

3.6 Insertion loss 0.10dBmax (DC~3GHz), 0.20dBmax (3~6GHz)

3.6.1 Test Methods:



- | | |
|-------------------|-------------|
| ① Port 1 | ④ 818000251 |
| ② SMA Jack | ⑤ Port 2 |
| ③ Microstrip line | |



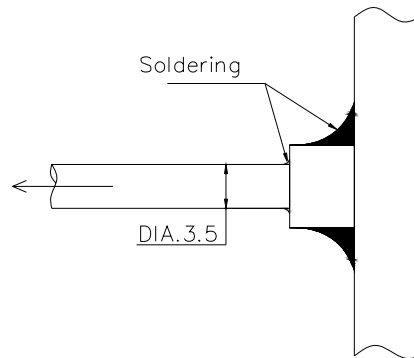
Product Specification

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Part Number:	KH-3030175-Y1	Checker/Date	Inspector/Date	Maker/Date	
		Henry 06/01/18'	Henry 06/01/18'	SAM 06/01/18'	

4 Mechanical Performance

- 4.1 Contact Stress 3.4N~4.5N
- 4.2 Mating Force 30N max
- 4.3 Unmating Force 5N~40N
- 4.4 Durability 500 cycles
- 4.5 Adhered Force of Solders 50N

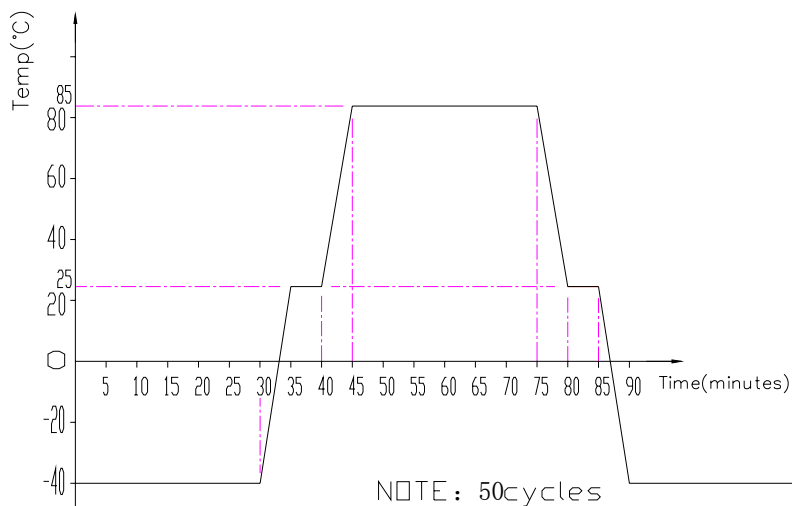
4.5.1 Test Methods:



- 4.6 Shock Acceleration: 750m/s² (Peak);
Duration of Shock: 6m sec.
Wave form: Half-sine
- 4.7 Vibration 10Hz~30Hz : 3mm

5 Environment Performance

5.1 Thermal Shock

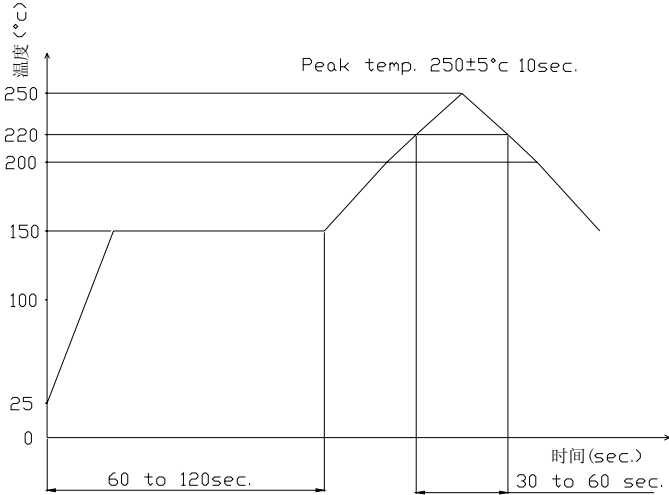


5.2 Static Humidity & Thermal Test

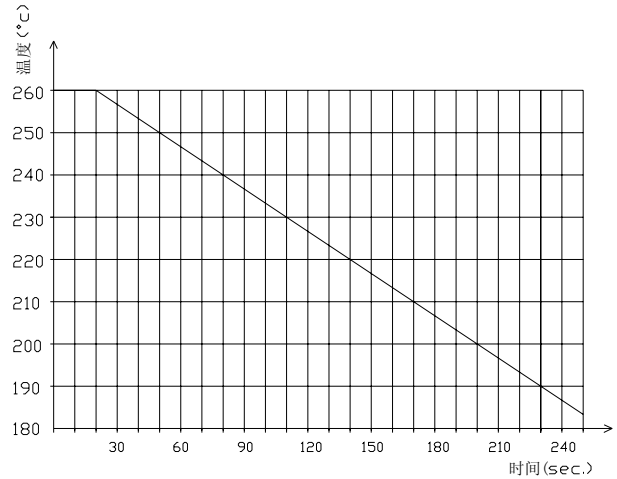
- Temperature: 60°C
- Humidity: 95% RH
- Time: 96 hours

6、SMT Temperature Curve

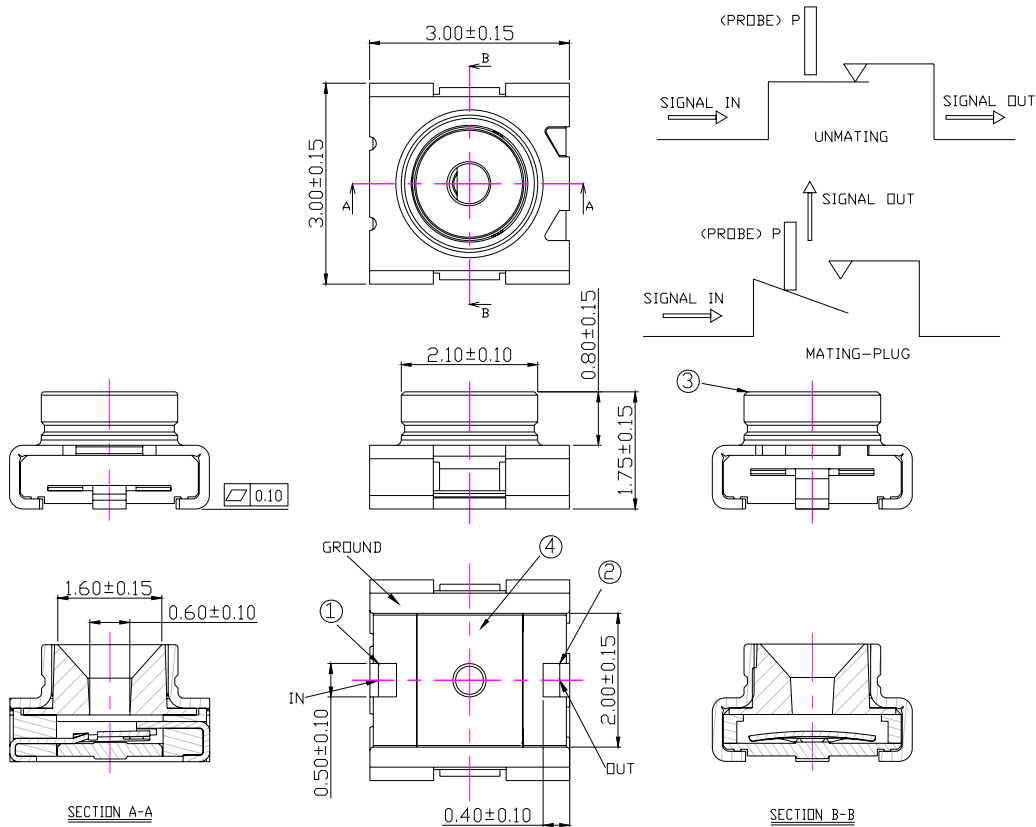
6.1 Reflow Soldering Standard Conditions



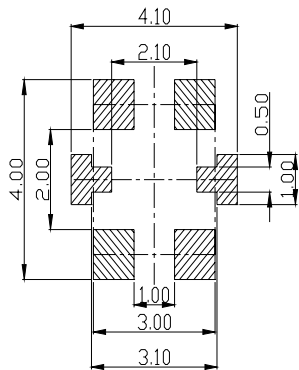
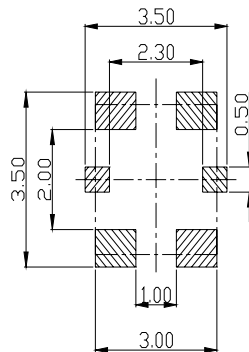
6.2 Allowable Temperature and Time of Reflow Soldering



7、Appearance Dimension

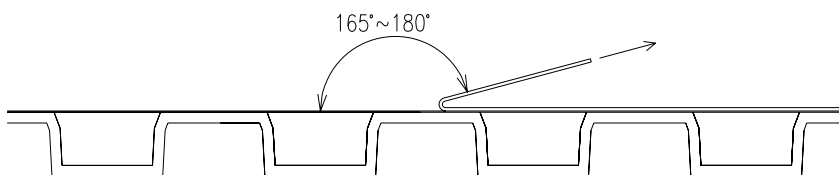
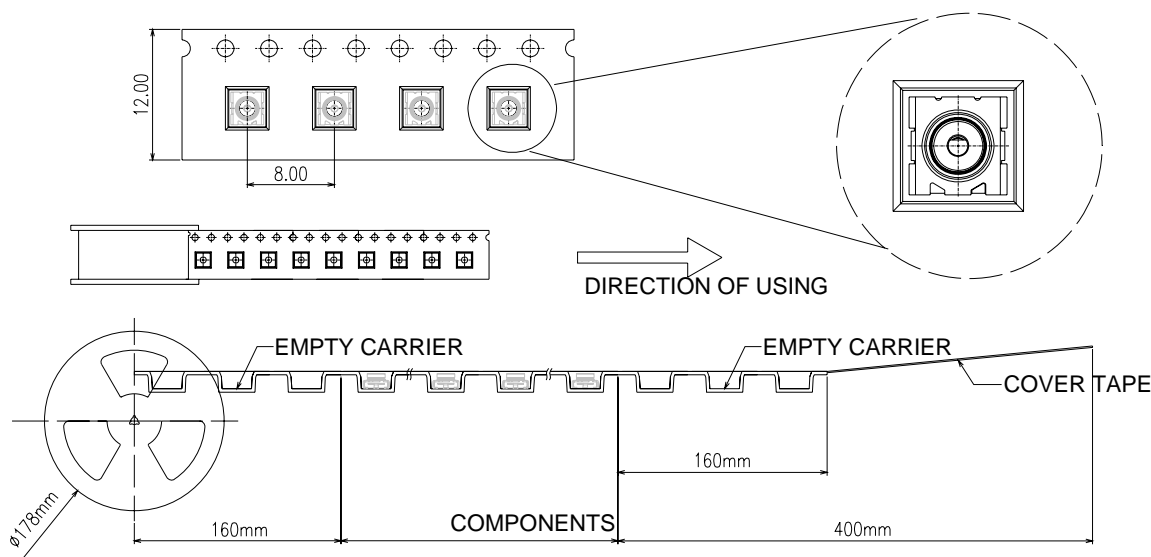


4	Case	Engineering plastic	UL 94V-0, BLACK	1
3	Output terminal	Copper Alloy	50u"Ni Overall, Contact Area Au2u", Soldering Area Gold Flash	1
2	Input terminal(R)	Copper Alloy	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
1	Input terminal(C)	Stainless Steel	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
No.	Part Name	Material	Finish	Q'ty

8、Printed circuit board (PCB) pad

 Recommend PCB Layout
General Tolerance: ± 0.05

 The standard solder stencil mask pattern
(Mask thickness 0.15mm)

9、PACKING SPECIFICATION
9.1 Peeling off Force of Cover Tape

When cover tape is peeled off as in right figure by a speed of 300mm/minute. The peeling off force should be 1.3N maximum.


9.2 THE WAY OF PACKAGE : TAPE PACKING, 1000Pcs/REEL (Φ178mm)

10、Storage Conditions

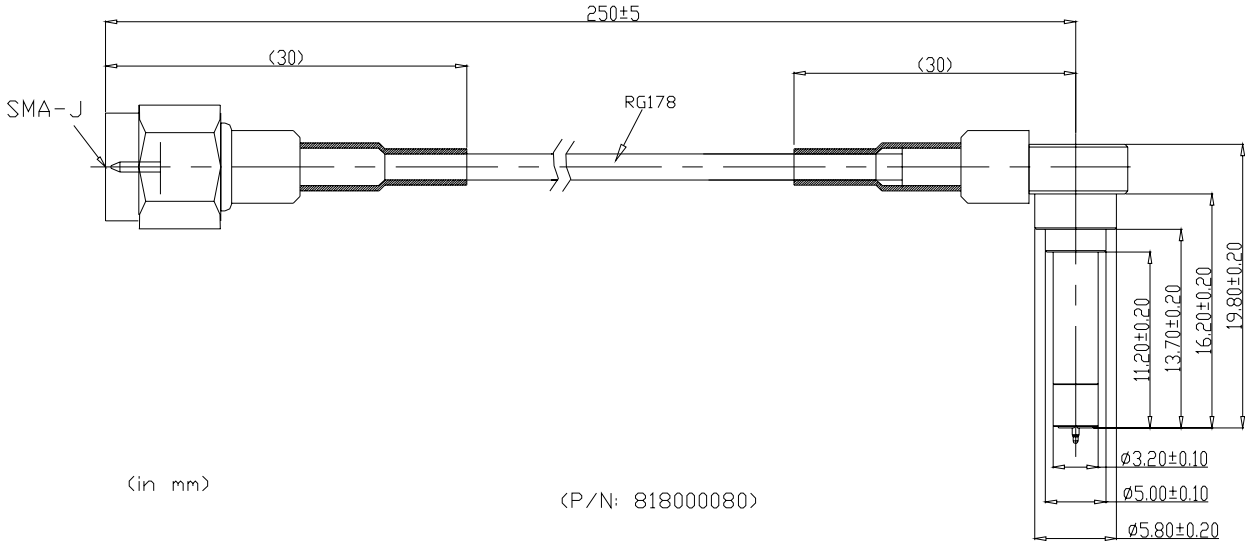
 Temperature: $-10 \sim +40$ °C

Moisture: 15~85 % RH

Valid Period: 6 months

11、Accessories for Tests

TYPE I :



TYPY II :

